

# Noninverting Buffer with Open Drain Output

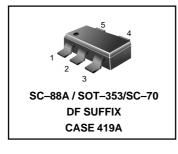


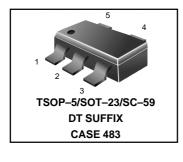
The MC74VHC1G07 is an advanced high speed CMOS buffer with open drain output fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer and an open drain output which provides the capability to set the output switching level. This allows the MC74VHC1G07 to be used to interface 5 V circuits to circuits of any voltage between V  $_{cc}$  and 7 V using an external resistor and power supply.

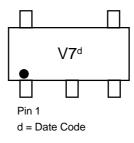
The MC74VHC1G07 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage.

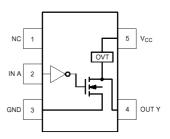
- High Speed:  $t_{PD}$  = 3.8 ns (Typ) at V <sub>CC</sub> = 5 V
- Low Internal Power Dissipation: I  $_{CC}$  = 2 mA (Max) at T  $_{A}$  = 25°C
- Power Down Protection Provided on Inputs
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FET = 105; Equivalent Gate = 26

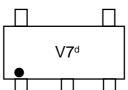




# MARKING DIAGRAMS







Pin 1

d = Date Code





Figure 2. Logic Symbol

PIN AS	PIN ASSIGNMENT								
1	NC								
2	IN A								
3	GND								
4	OUT Y								
5	V cc								

#### **FUNCTION TABLE**

Inputs	Output
А	Ϋ́
L	L
Н	Z

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.



# LESHAN RADIO COMPANY, LTD.

### MC74VHC1G07

#### **MAXIMUM RATINGS**

Symbol	Param	neter	Value	Unit
V <sub>cc</sub>	DC Supply Voltage		- 0.5 to + 7.0	V
V in	DC Input Voltage		- 0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		- 0.5 to +7.0	V
l <sub>ik</sub>	Input Diode Current		-20	mA
I <sub>ок</sub>	Output Diode Current	V <sub>out</sub> < GND; V <sub>out</sub> > V <sub>cc</sub>	+20	mA
I <sub>OUT</sub>	DC Output Current, per Pin		+ 25	mA
I <sub>cc</sub>	DC Supply Current, V cc and C	GND	+50	mA
P <sub>D</sub>	Power dissipation in still air	SC–88A, TSOP–5	200	mW
$\theta_{JA}$	Thermal resistance	SC–88A, TSOP–5	333	°C/W
T∟	Lead Temperature, 1 mm from	n Case for 10 s	260	°C
ΤJ	Junction Temperature Under B	Bias	+ 150	°C
T stg	Storage temperature		-65 to +150	°C
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2)	>2000	V
		Machine Model (Note 3)	> 200	
		Charged Device Model (Note 4)	N/A	
LATCH-UP	Latch–Up Performance Abo	ove V <sub>cc</sub> and Below GND at 125°C (Note 5)	± 500	mA

1. Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

2. Tested to EIA/JESD22-A114-A

3. Tested to EIA/JESD22-A115-A

4. Tested to JESD22–C101–A

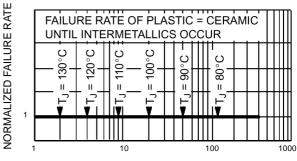
5. Tested to EIA/JESD78

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>cc</sub>	DC Supply Voltage	2.0	5.5	V	
V IN	DC Input Voltage	0.0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage		0.0	7.0	V
Τ <sub>A</sub>	Operating Temperature Range		- 55	+ 125	°C
t <sub>r</sub> ,t <sub>f</sub>	Input Rise and Fall Time	$V_{cc} = 3.3 \pm 0.3 V$	0	100	ns/V
		$V_{cc} = 5.0 \pm 0.5 V$	0	20	

#### DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction	Time,	Time,
Temperature °C	Hours	Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0



TIME, YEARS

Figure 3. Failure Rate vs. Time Junction Temperature



## LESHAN RADIO COMPANY, LTD.

### MC74VHC1G07

#### DC ELECTRICAL CHARACTERISTICS

			V <sub>cc</sub>	Т	<sub>A</sub> = 25	°C	$T_A \leq$	<b>85</b> °C	-55°C≤	Г <sub>А</sub> ≤125°C	
Symbol	Parameter	<b>Test Conditions</b>	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V IH	Minimum High–Level		2.0	1.5			1.5		1.5		V
	Input Voltage		3.0	2.1			2.1		2.1		
			4.5	3.15			3.15		3.15		
			5.5	3.85			3.85		3.85		
V IL	Maximum Low-Level		2.0			0.5		0.5		0.5	V
	Input Voltage		3.0			0.9		0.9		0.9	
			4.5			1.35		1.35		1.35	
			5.5			1.65		1.65		1.65	
V <sub>он</sub>	Minimum High–Level	$V_{IN} = V_{IH} \text{ or } V_{IL}$	2.0	1.9	2.0		1.9		1.9		V
	Output Voltage	I <sub>OH</sub> = − 50 μA	3.0	2.9	3.0		2.9		2.9		
	$V_{IN} = V_{IH} \text{ or } V_{IL}$		4.5	4.4	4.0		4.4		4.4		
		$V_{IN} = V_{IH} \text{ or } V_{IL}$									
		I <sub>он</sub> =4 mA	3.0	2.58			2.48		2.34		
		I <sub>он</sub> =8 mА	4.5	3.94			3.80		3.66		
V <sub>ol</sub>	Maximum Low–Level	$V_{IN} = V_{IH} \text{ or } V_{IL}$	2.0		0.0	0.1		0.1		0.1	V
	Output Voltage	I <sub>OL</sub> = 50 μA	3.0		0.0	0.1		0.1		0.1	
	$V_{IN} = V_{IH} \text{ or } V_{IL}$		4.5		0.0	0.1		0.1		0.1	
		$V_{IN} = V_{IH} \text{ or } V_{IL}$									
		$I_{OL} = 4 \text{ mA}$	3.0			0.36		0.44		0.52	
		I <sub>oL</sub> =8 mA	4.5			0.36		0.44		0.52	
I <sub>IN</sub>	Maximum Input	V $_{IN}$ = 5.5 V or GND	0 to5.5			±0.1		±1.0		±1.0	μΑ
	Leakage Current										
I <sub>cc</sub>	Maximum Quiescent	$V_{IN} = V_{CC} \text{ or } GND$	5.5			2.0		20		40	μΑ
	Supply Current										
I OPD	Maximum Off-state	V <sub>out</sub> = 5.5 V	0			0.25		2.5		5.0	μA
	Leakage Current										

#### AC ELECTRICAL CHARACTERISTICS C $_{load}$ = 50 pF, Input t $_{r}$ = t $_{f}$ = 3.0 ns

			T <sub>A</sub> = 25°C		$T_A \leq$	<b>85</b> °C	<b>55</b> °C t	o 125°C		
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t PZL	Maximum Output	V CC = 3.3 ± 0.3 V C L = 15 pF		5.0	7.1		8.5		10.0	ns
	Enable Time, Input A to Y	$R L = R I = 500 \Omega$ $C L = 50 pF$		7.5	10.6		12.0		14.5	
		$V CC = 5.0 \pm 0.5 V$ $C L = 15 pF$		3.8	5.5		6.5		8.0	
		$R L = R I = 500 \Omega$ $C L = 50 pF$		5.3	7.5		8.5		10.0	
t PLZ	Maximum Output Disable Time	$V CC = 3.3 \pm 0.3 V$ $C L = 50 pF$ $R L = R I = 500 \Omega$		7.5	10.6		12.0		14.5	ns
		V CC = $5.0 \pm 0.5$ V C L = $50$ pF R L = R I = $500$ Ω		5.3	7.5		8.5		10.0	
C IN	Maximum Input			4	10		10		10	pF
	Capacitance									

		Typical @ 25°C, V $_{cc}$ = 5.0 V	
C PD	Power Dissipation Capacitance (Note 6)	18	pF

6. C <sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} X V_{CC} X f_{in} + I_{CC} C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_{D} = C_{PD} X V_{CC}^2 X f_{in} + I_{CC} X V_{CC}$ .



### MC74VHC1G07

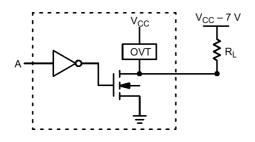


Figure 4. Output Voltage Mismatch Application

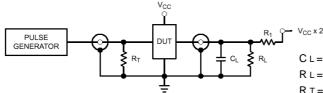
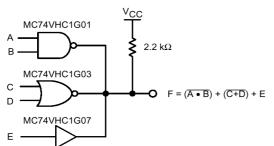


Figure 6. Test Circuit



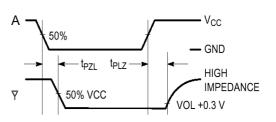
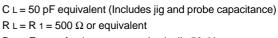


Figure 5. Switching Waveforms



R T = Z OUT of pulse generator (typically 50  $\Omega$ )

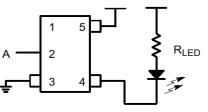


Figure 8. LED Driver

Figure 7. Complex Boolean Functions

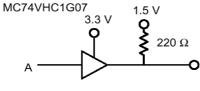


Figure 9. GTL Driver

#### **DEVICE ORDERING INFORMATION**

	Device Nomenclature										
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size			
MC74VHC1G07DFT1	MC	74	VHC1G	07	DF	T1	SC-70/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit			
MC74VHC1G07DFT2	MC	74	VHC1G	07	DF	T2	SC-70/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit			
MC74VHC1G07DFT4	MC	74	VHC1G	07	DF	T4	SC-70/SC-88A/ SOT-353	330 mm (13 in) 10,000 Unit			
MC74VHC1G07DTT1	MC	74	VHC1G	07	DT	T1	SOT-23/TSOPS/ SC-59	178 mm (7 in) 3000 Unit			
MC74VHC1G07DTT3	MC	74	VHC1G	07	DT	T3	SOT-23/TSOPS/ SC-59	330 mm (13 in) 10,000 Unit			